

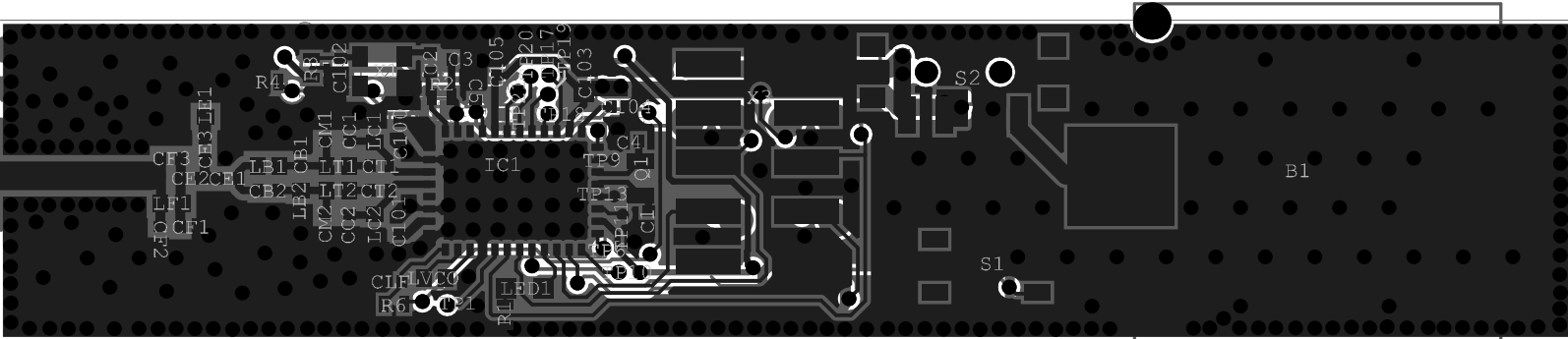
ICLB
AXM0F243-1-TX40
Ground pads under AXM0F243

ON SEMICONDUCTOR			
Title:	DVK-AXM0F243-868-1-ANT-GEVB	Rev:	1.1
Date:	7/9/2018	Sheet:	1

(C) ON SEMICONDUCTOR, 2011
DVK-AXM0F243-868-1-ANT

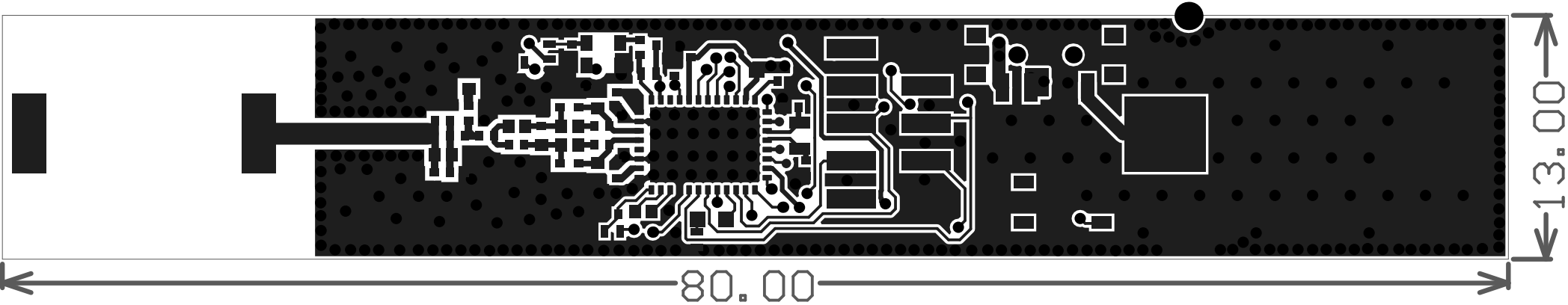


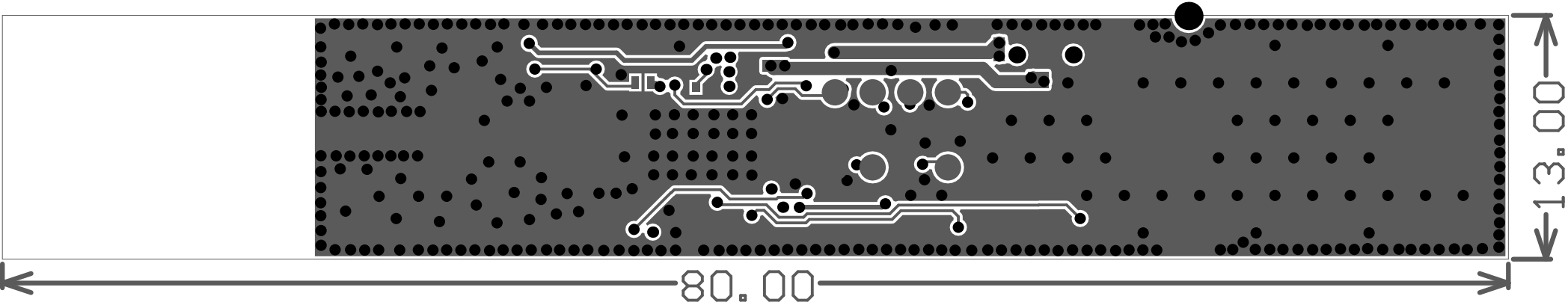
868 MHz / 48 MHz TCXO
REV 1.1



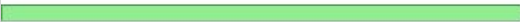








80.00

13.00





Board Stack Report

Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Paste			
2		Top Overlay			
3		Top Solder	Solder Resist	0.024mm	3.5
4		Top	Copper	0.054mm	
5		Dielectric 1	FR-4	1.000mm	4.8
6		Bottom	Copper	0.054mm	
7		Bottom Solder	Solder Resist	0.024mm	3.5
8		Bottom Overlay			
9		Bottom Paste			
	Height : 1.156mm				







